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Lin et al.

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(54) **METHOD FOR MANUFACTURING LIGHT EMITTING DIODE PACKAGING STRUCTURE**

(58) **Field of Classification Search**
CPC H01L 33/62; H01L 33/0095; H01L 33/58;
H01L 2933/0058; H01L 2933/0066
See application file for complete search history.

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(21) Appl. No.: **17/653,462**

(57) **ABSTRACT**

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A method for manufacturing a light emitting diode packaging structure includes the operations below. A flexible substrate having a first surface and a second surface is provided. A carrier substrate is formed on the first surface. An adhesive layer is formed on the second surface. A micro light emitting element is formed on the adhesive layer. The micro light emitting element has a conductive pad thereon opposite to the adhesive layer. A redistribution layer is formed and covers the micro light emitting element and the adhesive layer, wherein the redistribution layer includes a circuit layer electrically connecting to the conductive pad and an insulating layer covering the circuit layer. An electrode pad is formed on the redistribution layer and electrically connected to the circuit layer, wherein a total thickness of the flexible substrate, the adhesive layer, the redistribution layer, and the electrode pad is less than 200 um.

(65) **Prior Publication Data**

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(51) **Int. Cl.**

H01L 33/62 (2010.01)

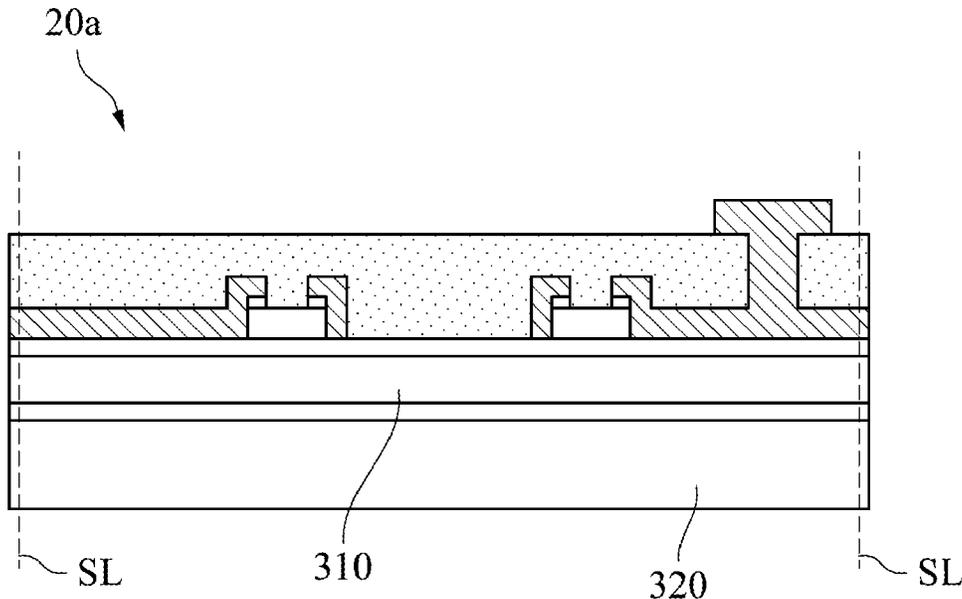
H01L 33/58 (2010.01)

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12 Claims, 6 Drawing Sheets



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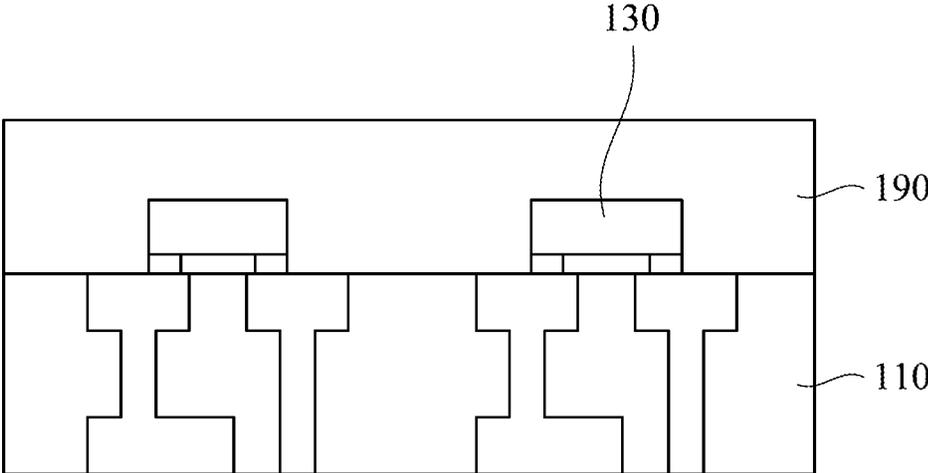


Fig. 1

20a

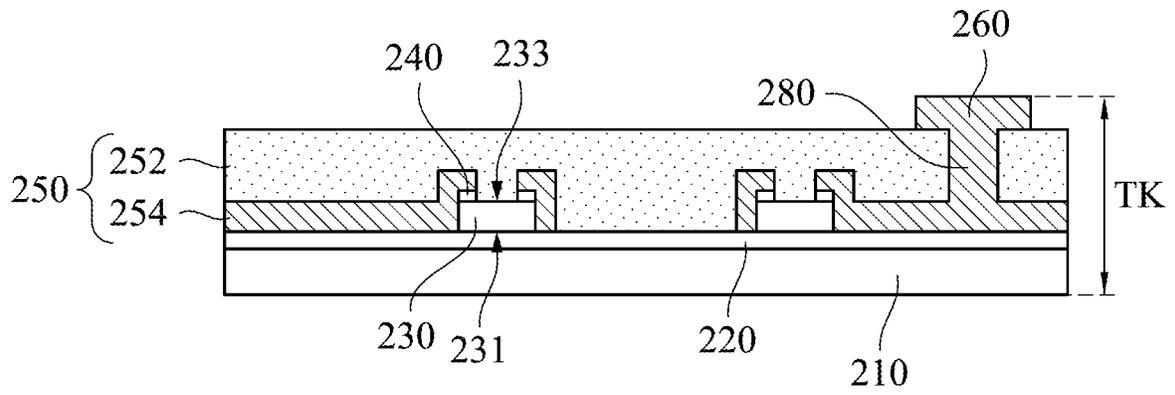


Fig. 2A

20b

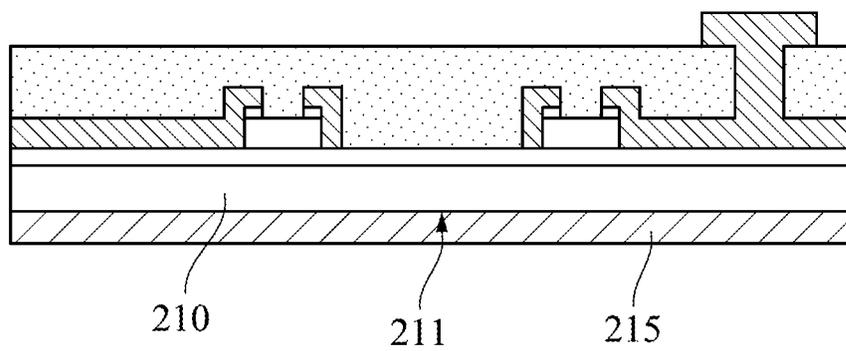


Fig. 2B

20c

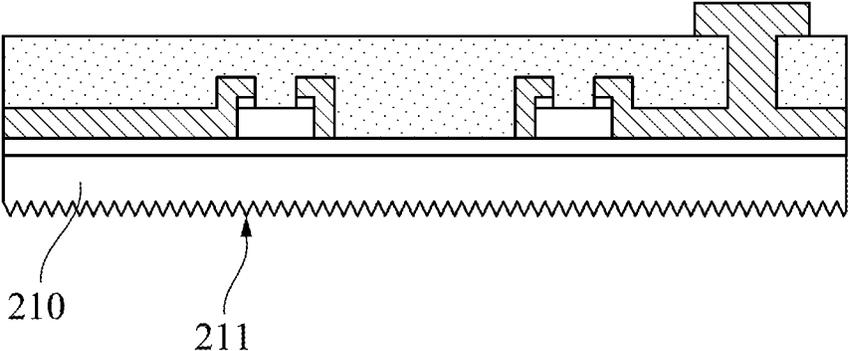


Fig. 2C

20d

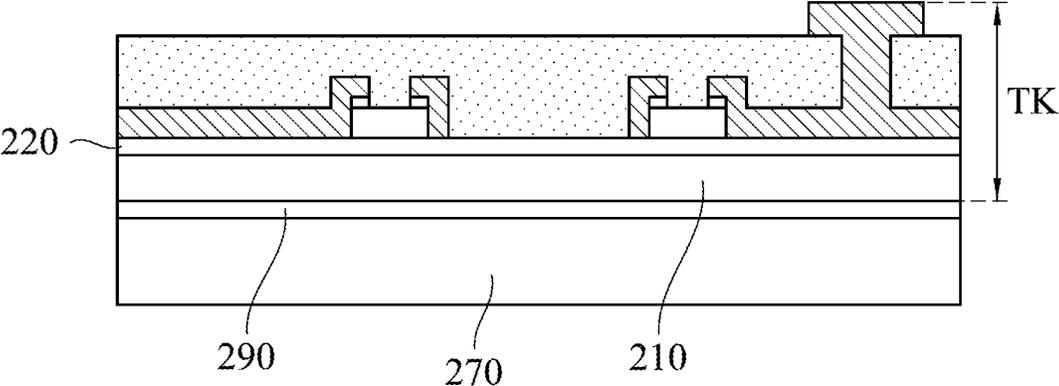


Fig. 2D

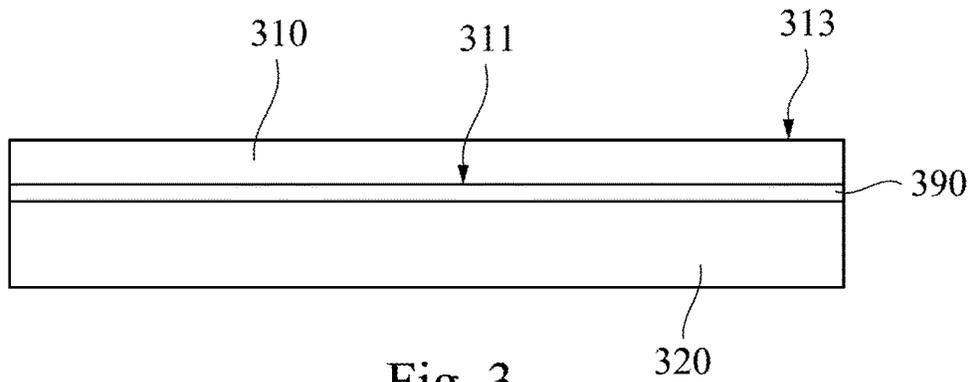


Fig. 3

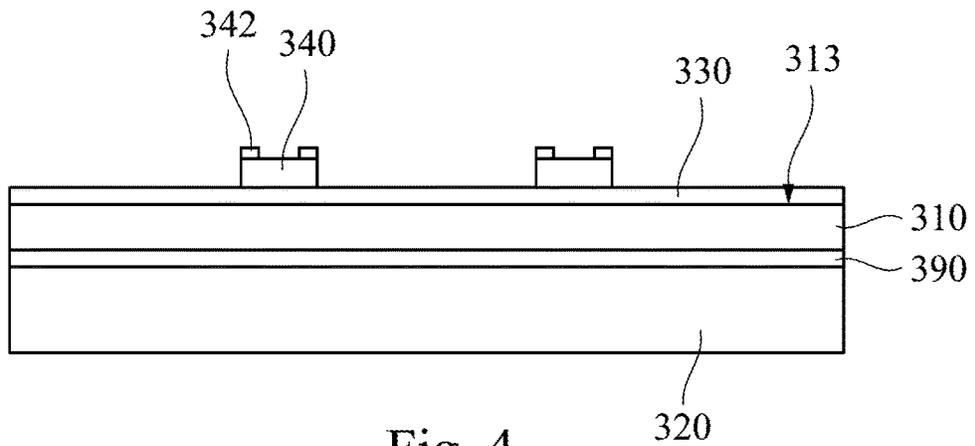


Fig. 4

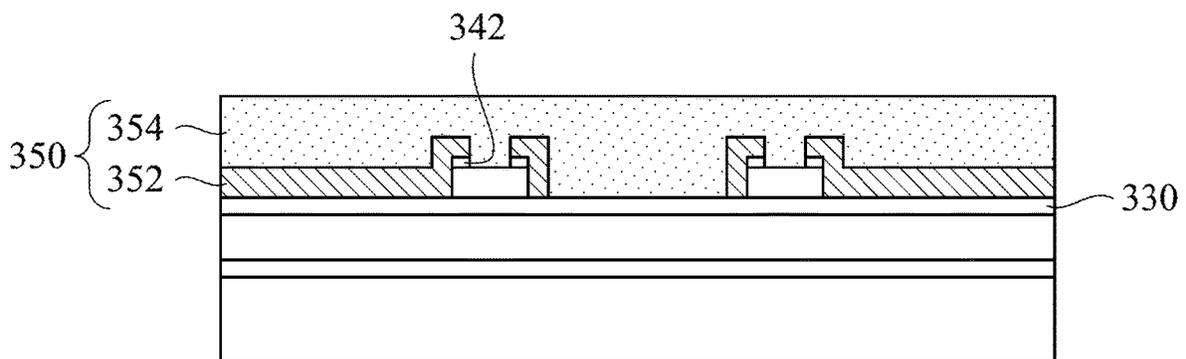


Fig. 5

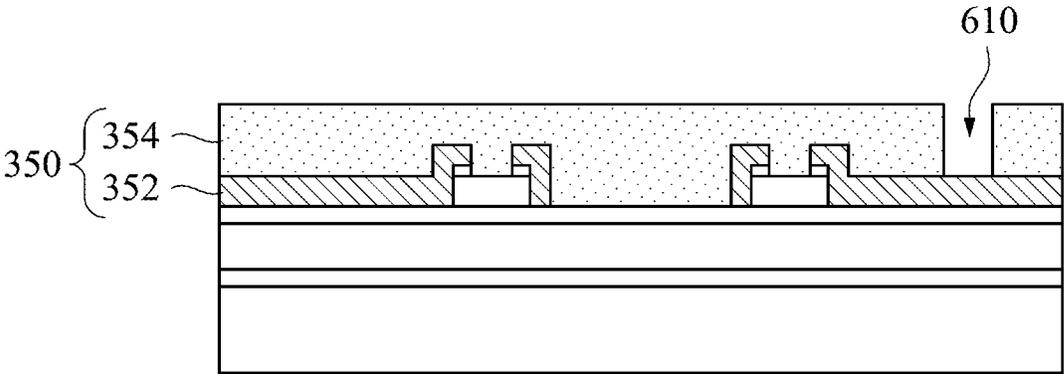


Fig. 6

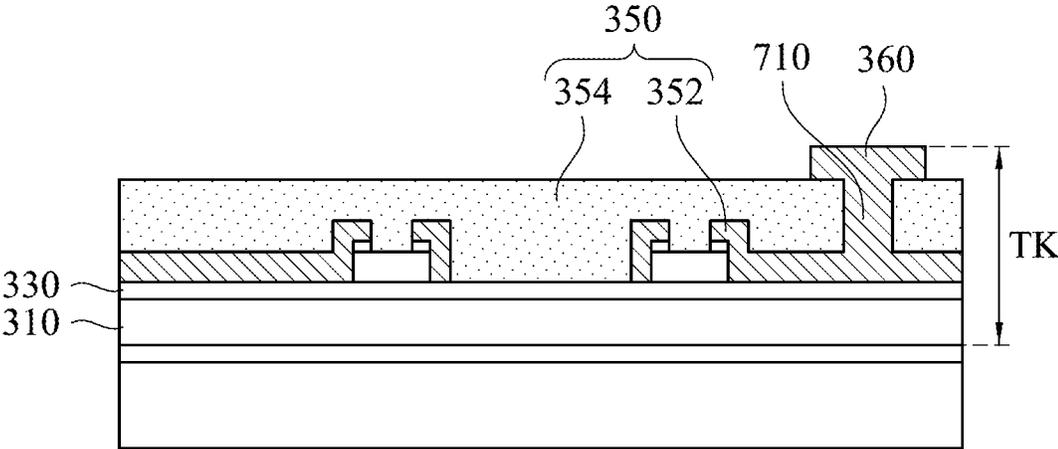


Fig. 7

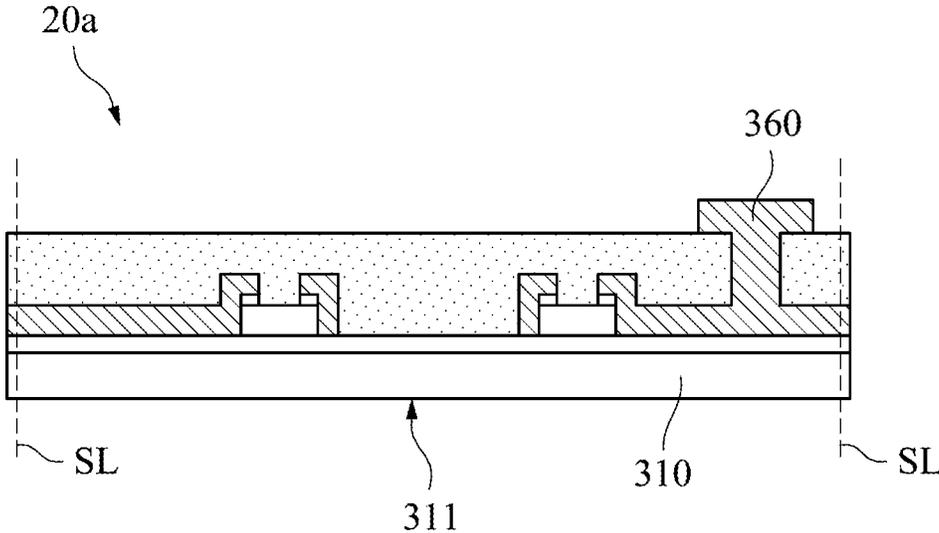


Fig. 8A

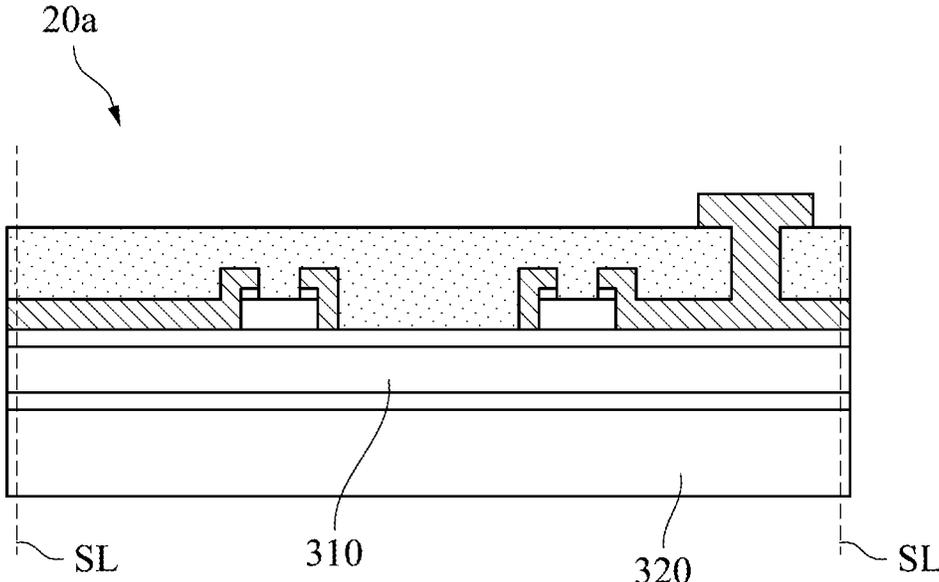


Fig. 8B

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METHOD FOR MANUFACTURING LIGHT EMITTING DIODE PACKAGING STRUCTURE

CROSS-REFERENCE TO RELATED APPLICATION

The present application is a Divisional Application of the U.S. application Ser. No. 16/944,131, filed Jul. 30, 2020, which is herein incorporated by reference in its entirety.

BACKGROUND

Field of Invention

The present disclosure relates to a method for manufacturing a light emitting diode packaging structure.

Description of Related Art

Compared with the traditional illumination source, the light emitting diode (LED) has the advantages of light weight, small volume, low pollution and long life. It has been used as a new type of illumination source. In various fields, such as street lamps, traffic lights, signal lights, spotlights and decorative lights. A typical light emitting diode packaging structure includes a rigid printed circuit board, a light emitting chip disposed on the rigid printed circuit board and electrically connected to the circuits in the rigid printed circuit board, and an encapsulate layer disposed on the rigid printed circuit board and sealing the light emitting chip. In general, the typical light emitting diode packaging structure has a greater thickness due to the rigid printed circuit board and the circuits should be thick enough for providing sufficient strength when forming the encapsulate layer.

In order to satisfy user demand for light, thin, short, and small electronic devices, the size of light emitting diode packages is getting smaller day by day. In view of the above, it is necessary to provide a light emitting diode package structure having a thinner thickness and a method of manufacturing thereof.

SUMMARY

According to an aspect of the present disclosure, a method for manufacturing a light emitting diode packaging structure is provided. The method includes the operations below. A flexible substrate having a first surface and a second surface opposite thereof is provided. A carrier substrate is formed on the first surface. An adhesive layer is formed on the second surface. A micro light emitting element is formed on the adhesive layer, wherein the micro light emitting element has a conductive pad thereon opposite to the adhesive layer. A redistribution layer is formed and covers the micro light emitting element and the adhesive layer, wherein the redistribution layer includes a circuit layer electrically connecting to the conductive pad and an insulating layer covering the circuit layer. An electrode pad is formed on the redistribution layer and electrically connected to the circuit layer, wherein a total thickness of the flexible substrate, the adhesive layer, the redistribution layer, and the electrode pad is less than 200 μm .

In some embodiments of the present disclosure, the method further includes the operations below. After forming the electrode pad, the carrier substrate is removed. The

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flexible substrate is diced along a scribe line to form a plurality of light emitting diode packaging structures.

In some embodiments of the present disclosure, the method further includes the operations below. After removing the carrier substrate, texturing the first surface of the flexible substrate is textured.

In some embodiments of the present disclosure, the first surface of the flexible substrate of each of the light emitting diode packaging structures is an uneven surface.

In some embodiments of the present disclosure, the method further includes the operations below. A microstructure is formed on the first surface of the flexible substrate.

In some embodiments of the present disclosure, the microstructure includes an optical lens, an optical coating layer, or an optical film.

In some embodiments of the present disclosure, the method further includes the operations below. After removing the carrier substrate, the first surface of the flexible substrate is flattened.

In some embodiments of the present disclosure, the method further includes the operations below. After forming the electrode pad, the flexible substrate is diced along a scribe line to form a plurality of light emitting diode packaging structure.

In some embodiments of the present disclosure, the method further includes the operations below. Before forming the electrode pad and after forming the redistribution layer, a conductive via is formed in the redistribution layer so that the conductive via electrically connects the electrode pad to the circuit layer.

In some embodiments of the present disclosure, the method further includes the operations below. An alignment mark is formed on the carrier substrate.

In some embodiments of the present disclosure, a portion of the circuit layer is in direct contact with the adhesive layer.

BRIEF DESCRIPTION OF THE DRAWINGS

The invention can be more fully understood by reading the following detailed description of the embodiment, with reference made to the accompanying drawings as follows:

FIG. 1 is a cross-sectional view illustrating a light emitting diode packaging structure according to one comparative example of the present disclosure.

FIGS. 2A, 2B, 2C, and 2D are cross-sectional views illustrating a light emitting diode packaging structure according to various embodiments of the present disclosure.

FIGS. 3, 4, 5, 6, 7, 8A, and 8B are cross-sectional views illustrating various process stages of manufacturing the light emitting diode packaging structure according to various embodiments of the present disclosure.

DETAILED DESCRIPTION

Reference will now be made in detail to the present embodiments of the invention, examples of which are illustrated in the accompanying drawings. Wherever possible, the same reference numbers are used in the drawings and the description to refer to the same or like parts. Reference will now be made in detail to the present embodiments of the disclosure, examples of which are illustrated in the accompanying drawings. Wherever possible, the same reference numbers are used in the drawings and the description to refer to the same or like parts.

The terms “about” and “approximately” in the disclosure are used as equivalents. Any numerals used in this disclosure

with or without “about,” “approximately,” etc. are meant to cover any normal fluctuations appreciated by one of ordinary skill in the relevant art. In certain embodiments, the term “approximately” or “about” refers to a range of values that fall within 20%, 10%, 5%, or less in either direction (greater or less than) of the stated reference value unless otherwise stated or otherwise evident from the context.

FIG. 1 is a cross-sectional view illustrating a light emitting diode packaging structure **10** according to one comparative example of the present disclosure. Referring to FIG. 1, the light emitting diode packaging structure **10** disclosed herein includes a rigid substrate **110**, a light emitting element **130**, and an encapsulation layer **190**. To be specific, the rigid substrate **110** is a rigid printed circuit board (PCB). The rigid substrate **110** may include epoxy molding compound (EMC). In addition, the rigid substrate **110** may further include metallic circuits, such as, copper circuits, iron circuits, or other alloy circuit with good conductivity. For example, the rigid substrate **110** may be a FR-4 substrate, BT substrate, or a molded interconnect substrate (MIS).

As shown in FIG. 1, the light emitting element **130** is disposed on the rigid substrate **110** and electrically connected to the circuit layer in the rigid substrate **110**. The encapsulation layer **190** is disposed on the rigid substrate **110** and covers the light emitting element **130**. It would be understood that a total thickness of the light emitting diode packaging structure **10** using the rigid printed circuit board and known molding process is usually greater than 200 μm .

FIG. 2A is a cross-sectional view illustrating a light emitting diode packaging structure **20a** according to various embodiments of the present disclosure. The light emitting diode packaging structure **20a** includes a flexible substrate **210**, a first adhesive layer **220**, a micro light emitting element **230**, a conductive pad **240**, a redistribution layer **250**, and an electrode pad **260**. To be specific, the flexible substrate **210** may include transparent materials so as to meet the requirement of the transparent display. In some embodiments of the present disclosure, the flexible substrate **210** may include polyimide, polyethylene terephthalate, poly(ethylene naphthalate), polycarbonate, glass or a combination thereof. It can be understood that the flexible substrate **210** is used to decrease an overall thickness of the light emitting diode packaging structure **20a** and provides flexibility for the light emitting diode packaging structure **20a**. It should be noted that the thickness of the flexible substrate **210** is less than 100 μm . In some embodiments of the present disclosure, a bottom surface **211** of the flexible substrate **210** may be an even surface or an uneven surface to increase the light efficiency or modify the light profile. It can be understood that the bottom surface **211** of the flexible substrate **210** may be a light emitting surface. In addition, another surface opposite to the bottom surface **211** of the flexible substrate may also be a light emitting surface.

As shown in FIG. 2A, the first adhesive layer **220** is disposed on the flexible substrate **210**. In some embodiments of the present disclosure, the first adhesive layer **220** may include insulating glue. For example, the material of the first adhesive layer **220** may be insulating glue such as epoxy resin or silicone, but not limited thereto.

As shown in FIG. 2A, the micro light emitting element **230** is disposed on the first adhesive layer **220**. Specifically, the micro light emitting element **230** has a first surface **231** facing to the first adhesive layer **220** and a second surface **233** opposite to the first surface **231**. Although a number of the micro light emitting element **230** as shown in FIG. 2A is two, the number of the micro light emitting element **230** may be 3, 4, 5, 6, or more according to demand. The micro light

emitting element **230** may emit red light, green light, blue light, or white light, but not limited thereto.

As shown in FIG. 2A, the conductive pad **240** is disposed on the second surface **233** of the micro light emitting element **230**. In some embodiments of the present disclosure, the conductive pad **240** may include conductive materials, such as copper, nickel, gold, aluminum, tungsten, iron, or alloys of above metals.

As shown in FIG. 2A, the redistribution layer **250** covers the micro light emitting element **230** and the conductive pad **240**. Specifically, the redistribution layer **250** includes an insulating layer **252** and a circuit layer **254** embedded in the insulating layer **252**, and the circuit layer **254** is electrically connected to the conductive pad **240**. It should be noted that the insulating layer **252** is transparent, so that the light emitted from the micro light emitting element **230** can pass through the insulating layer **252** to the outside of the light emitting diode packaging structure **20a**. It can be understood that the insulating layer **252** could also be used as a protective layer. Specifically, because the insulating layer **252** covers the micro light emitting element **230** and the circuit layer **254**, the insulating layer **252** can block moisture permeation and avoid oxidation of the circuit layer **254**. Therefore, the light emitting diode packaging structure **20a** of the present disclosure is not necessary to additionally include a protective layer. Although the number of the redistribution layer **250** is one as shown in FIG. 2A, the number of the redistribution layer **250** can be two, three, or four according to design requirements.

In some embodiments of the present disclosure, the insulating layer **252** may include poly(methyl methacrylate) (PMMA), polyethylene terephthalate (PET), polystyrene (PS), polypropylene (PP), polyamide (PA), polycarbonate (PC), epoxy, silicon, and/or a combination thereof. In some embodiments of the present disclosure, the circuit layer **254** may include copper, nickel, gold, aluminum, tungsten, iron, or alloys of above metals. In some embodiments of the present disclosure, a portion of the circuit layer **254** is in direct contact with the first adhesive layer **220** as shown in FIG. 2A.

As shown in FIG. 2A, the electrode pad **260** is disposed on the redistribution layer **250** and electrically connected to the circuit layer **254**. It is noted that a total thickness TK of the flexible substrate **210**, the first adhesive layer **220**, the redistribution layer **250**, and the electrode pad **260** is less than 200 μm . For example, the total thickness TK of the flexible substrate **210**, the first adhesive layer **220**, the redistribution layer **250**, and the electrode pad **260** may be about 100 μm , 110 μm , 120 μm , 130 μm , 140 μm , 150 μm , 160 μm , 170 μm , 180 μm , or 190 μm . In some embodiments of the present disclosure, the electrode pad **260** may include copper, nickel, gold, aluminum, tungsten, iron, or alloys of above metals.

In some embodiments of the present disclosure, the light emitting diode packaging structure **20a** further includes a conductive via **280** electrically connecting the electrode pad **260** to the circuit layer **254**. The material of the conductive via **280** may be the same as or similar to the material of the electrode pad **260**.

FIG. 2B is a cross-sectional view illustrating a light emitting diode packaging structure **20b** according to various embodiments of the present disclosure. The light emitting diode packaging structure **20b** of FIG. 2B is similar to that of FIG. 2A. The difference between the light emitting diode packaging structure **20b** and the light emitting diode packaging structure **20a** of the previous embodiment is that, in this embodiment, the light emitting diode packaging struc-

ture **20b** further includes a microstructure **215** disposed on the bottom surface **211** of the flexible substrate **210**. In some embodiments of the present disclosure, the microstructure **215** may include an optical lens, an optical coating layer, or an optical film. For example, the optical lens may include resin, plastic, glass, or sapphire, but not limited thereto. The optical coating layer may include SiN_x , SiO_x , TiO_2 , Al_2O_3 , or MgF_2 , but not limited thereto. The optical film may be a linear polarizer, a circular polarizer, or a phase compensation plate, but not limited thereto.

FIG. **2C** is a cross-sectional view illustrating a light emitting diode packaging structure **20c** according to various embodiments of the present disclosure. The light emitting diode packaging structure **20c** of FIG. **2C** is similar to that of FIG. **2A**. The difference between the light emitting diode packaging structure **20c** and the light emitting diode packaging structure **20a** of the previous embodiment is that, in this embodiment, the bottom surface **211** of the flexible substrate **210** of the light emitting diode packaging structure **20c** is an uneven surface. Specifically, the bottom surface **211** of the flexible substrate **210** of the light emitting diode packaging structure **20b** may have a roughness by a surface roughening treatment.

FIG. **2D** is a cross-sectional view illustrating a light emitting diode packaging structure **20d** according to various embodiments of the present disclosure. The light emitting diode packaging structure **20d** of FIG. **2D** is similar to that of FIG. **2A**. The difference between the light emitting diode packaging structure **20d** and the light emitting diode packaging structure **20a** of the previous embodiment is that, in this embodiment, the light emitting diode packaging structure **20d** further includes a carrier substrate **270** and a second adhesive layer **290**. To be specific, the carrier substrate **270** is disposed on the bottom surface **211** of the flexible substrate **210**. The second adhesive layer **290** is disposed between the carrier substrate **270** and the flexible substrate **210** to increase the bonding force between the carrier substrate **270** and the flexible substrate **210**. The material of the second adhesive layer **290** may be the same as or similar to the material of the first adhesive layer **220**. In some embodiments of the present disclosure, the carrier substrate **270** may include an alignment mark (not shown) thereon. In some embodiments of the present disclosure, the carrier substrate **270** may be transparent, translucent, or opaque. In some embodiments of the present disclosure, the carrier substrate **270** may include organic materials, inorganic materials, or metallic materials, but not limited thereto.

A method for manufacturing a light emitting diode packaging structure **20a** and **20d** is also provided herein. FIGS. **3**, **4**, **5**, **6**, **7**, **8A**, and **8B** are cross-sectional views illustrating various process stages of manufacturing the light emitting diode packaging structure **20a** and **20d** according to various embodiments of the present disclosure.

Referring to FIG. **3**, a flexible substrate **310** is provided. To be specific, the flexible substrate **310** has a first surface **311** and a second surface **313** opposite thereof. It should be noted that the material and other features of the flexible substrate **310** may be the same as or similar to that of the flexible substrate **210** shown in FIG. **2A**, and the description thereof is omitted.

As shown in FIG. **3**, a carrier substrate **320** is formed on the first surface **311** of the flexible substrate **310**. To be specific, the carrier substrate **320** is formed on the first surface **311** of the flexible substrate **310** by an adhesive layer **390**. It can be understood that the adhesive layer **390** can increase the bonding force between the carrier substrate **320** and the flexible substrate **310**. It should be noted that the

material and other features of the carrier substrate **320** and the adhesive layer **390** may be the same as or similar to that of the carrier substrate **270** and the second adhesive layer **290** shown in FIG. **2D**, and the description thereof is omitted. The carrier substrate **320** can provide support for various stages of a manufacturing the light emitting diode packaging structure **20a** and **20d**. In some embodiments of the present disclosure, an alignment mark (not shown) may be formed on the carrier substrate **320** to provide an alignment mark for various stages of a manufacturing the light emitting diode packaging structure **20a** and **20d**.

Referring to FIG. **4**, an adhesive layer **330** is formed on the second surface **313** of the flexible substrate **310**. In some embodiments of the present disclosure, the adhesive layer **330** fully covers the second surface **313** of the flexible substrate **310**. It should be noted that the material and other features of the adhesive layer **330** may be the same as or similar to that of the first adhesive layer **220** shown in FIG. **2A**, and the description thereof is omitted.

Referring to FIG. **4**, a micro light emitting element **340** is formed on the adhesive layer **330**. To be specific, the micro light emitting element **340** has a conductive pad **342** thereon opposite to the adhesive layer **330**. It should be noted that the material and other features of the micro light emitting element **340** and the conductive pad **342** may be the same as or similar to that of the micro light emitting element **230** and the conductive pad **240** shown in FIG. **2A**, and the description thereof is omitted.

Referring to FIG. **5**, a redistribution layer **350** covers the micro light emitting element **340** and the adhesive layer **330**. To be specific, the redistribution layer **350** includes a circuit layer **352** electrically connecting to the conductive pad **342** and an insulating layer **354** covering the circuit layer **352**. In some embodiments of the present disclosure, a portion of the circuit layer **352** is in direct contact with the adhesive layer **330**. In some embodiments of the present disclosure, the redistribution layer **350** could be formed by the redistribution layer (RDL) technical to achieve the effect of thin line width. It should be noted that the material and other features of the circuit layer **352** and the insulating layer **354** may be the same as or similar to that of the circuit layer **254** and the insulating layer **252** shown in FIG. **2A**, and the description thereof is omitted.

Referring to FIGS. **6-7**, an electrode pad **360** is formed on the redistribution layer **350** and electrically connected to the circuit layer **352**. In some embodiments of the present disclosure, before forming the electrode pad **360** and after forming the redistribution layer **350**, the method further includes forming a conductive via **710** in the redistribution layer **350** so that the conductive via **710** electrically connects the electrode pad **360** to the circuit layer **352**. For example, a through hole **610** may be first formed to penetrate the insulating layer **354** and therefore a portion of the circuit layer **352** is exposed from the through hole **610**. For example, the through hole **610** could be formed by lithography process, drilling process, laser drilling process, or other suitable processes. Next, a conductive material is filled up the through hole **610** to form the conductive via **710**. The electrode pad **360** then covers the conductive via **710**. It can be understood that the conductive via **710** and the electrode pad **360** can be formed separately or simultaneously. It is noted that a total thickness TK of the flexible substrate **310**, the adhesive layer **330**, the redistribution layer **350**, and the electrode pad **360** is less than 200 μm . For example, the total thickness TK of the flexible substrate **310**, the adhesive layer **330**, the redistribution layer **350**, and the electrode pad **360**

may be about 100 μm, 110 μm, 120 μm, 130 μm, 140 μm, 150 μm, 160 μm, 170 μm, 180 μm, or 190 μm.

Next, referring to FIG. 8A, after forming the electrode pad 360, the method further includes removing the carrier substrate 320 and dicing the flexible substrate 310 along a scribe line SL to form a plurality of light emitting diode packaging structure 20a. In some embodiments of the present disclosure, after removing the carrier substrate 320, the method further includes texturing the first surface 311 of the flexible substrate 310 or forming a microstructure (not shown) on the first surface 311 of the flexible substrate. For example, the microstructure is the same as or similar to the microstructure 215 shown in FIG. 2B, such as an optical lens, an optical coating layer, or an optical film. In some embodiments of the present disclosure, after removing the carrier substrate 320, the method further includes flattening the first surface 311 of the flexible substrate 310.

Alternatively, referring to FIG. 8B, after forming the electrode pad 360, the method further includes dicing the flexible substrate 310 along a scribe line SL to form a plurality of light emitting diode packaging structure 20d. It is noted that the carrier substrate 320 may not be removed.

From the embodiments described above of the present disclosure, the light emitting diode packaging structure and the method for manufacturing thereof can decrease the overall thickness to less than 200 μm. More specifically, the light emitting diode packaging structure of the present disclosure uses the flexible substrate to replace the core layer of the rigid substrate of traditional light emitting diode packaging structure, so that the overall thickness of the light emitting diode packaging structure can be reduced and flexible product requirements can be met. Moreover, the present disclosure also uses redistribution layer technology to reduce the thickness of the rigid substrate multilayer process.

Although the present disclosure has been described in considerable detail with reference to certain embodiments thereof, other embodiments are possible. Therefore, the spirit and scope of the appended claims should not be limited to the description of the embodiments contained herein.

It will be apparent to those skilled in the art that various modifications and variations can be made to the structure of the present disclosure without departing from the scope or spirit of the invention. In view of the foregoing, it is intended that the present disclosure cover modifications and variations of this invention provided they fall within the scope of the following claims.

What is claimed is:

1. A method for manufacturing a light emitting diode packaging structure, comprising: providing a flexible substrate having a first surface and a second surface opposite thereof; forming a carrier substrate on the first surface;

forming an adhesive layer on the second surface; forming a micro light emitting element on the adhesive layer, wherein the micro light emitting element has a conductive pad thereon opposite to the adhesive layer; forming a redistribution layer covering the micro light emitting element and the adhesive layer, wherein the redistribution layer comprises a circuit layer electrically connecting to the conductive pad and an insulating layer covering the circuit layer; and forming an electrode pad on the redistribution layer and electrically connecting to the circuit layer, wherein a total thickness of the flexible substrate, the adhesive layer, the redistribution layer, and the electrode pad is less than 200 μm.

2. The method of claim 1, further comprising: after forming the electrode pad, removing the carrier substrate; and dicing the flexible substrate along a scribe line to form a plurality of light emitting diode packaging structures.
3. The method of claim 2, further comprising: after removing the carrier substrate, texturing the first surface of the flexible substrate.
4. The method of claim 3, wherein the first surface of the flexible substrate of each of the light emitting diode packaging structures is an uneven surface.
5. The method of claim 2, further comprising: forming a microstructure on the first surface of the flexible substrate.
6. The method of claim 5, wherein the microstructure comprises an optical lens, an optical coating layer, or an optical film.
7. The method of claim 2, further comprising: after removing the carrier substrate, flattening the first surface of the flexible substrate.
8. The method of claim 1, further comprising: after forming the electrode pad, dicing the flexible substrate along a scribe line to form a plurality of light emitting diode packaging structures.
9. The method of claim 1, further comprising: before forming the electrode pad and after forming the redistribution layer, forming a conductive via in the redistribution layer so that the conductive via electrically connects the electrode pad to the circuit layer.
10. The method of claim 1, wherein the flexible substrate comprises polyimide, polyethylene terephthalate, poly(ethylene naphthalate), polycarbonate, glass or a combination thereof.
11. The method of claim 1, further comprising: forming an alignment mark on the carrier substrate.
12. The method of claim 1, wherein a portion of the circuit layer is in direct contact with the adhesive layer.

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